

# **Enhancement Mode N-Channel Power MOSFET**

SOP8/NMOS/20V/ $\pm$ 12V/0.75V/6A/18m $\Omega$ 

Rev0.3





# 20V, 18mΩ, 6A, N-Channel Enhancement Mode Power MOSFET

#### 1.Features

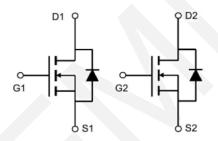
- ◆ High Power and current handing capability
- ◆ Lead free product is acquired
- Surface Mount Package

V <sub>DS</sub> Typ	R <sub>DS(on)</sub> Typ.	I <sub>D</sub> Max.
20V	18mΩ @ 4.5V	C.A.
	25mΩ @ 2.5V	6A

### 2.Applications

- Battery protection
- ◆ Load Switch
- Power management





Schematic Diagram

## 3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Tube	PCS/CTN.	
WP9926B	9926B	SOP8	4,000	48,000	

## 4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V <sub>DSS</sub>	20	V
Gate to Source Voltage	V <sub>GSS</sub>	V <sub>GSS</sub> ±12	
Drain Current-Continuous	I <sub>D</sub>	6	Α
Drain Current (Pulse)	Ірм	20	Α
Maximum Power Dissipation	PD	2	W
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### 5.Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 2)	Reja	56	°C/W

Note 2: When mounted on 1 inch square copper board t ≤ 10sec The value in any given application depends on the user's specific board design.



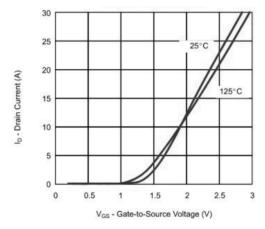
# 6.Electrical Characteristics at Ta=25°C (Note 3)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$I_D = 250 \mu A$ , $V_{GS} = 0 V$	20			V
Zero-Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 12V, V_{DS} = 0V$			±10	μA
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250µA	0.45	0.75	1.2	V
Drain to Source On-State		I <sub>D</sub> = 6A, V <sub>GS</sub> = 4.5V		18	24	mΩ
Resistance	R <sub>DS(on)</sub>	I <sub>D</sub> = 5A, V <sub>GS</sub> = 2.5V		25	33	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.7A, V <sub>GS</sub> = 0			1.4	V
Input Capacitance	Ciss	V <sub>GS</sub> =0V,		522		pF
Output Capacitance	Coss	V <sub>DS</sub> =8V,		98.5		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	Frequency=1.0MHz		75		pF
Turn-ON Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 10V,		10.5		ns
Turn-ON Rise Time	<b>t</b> r	$V_{GS} = 4.5V$ ,		4.5		ns
Turn-OFF Delay Time	$t_{d(off)}$	$R_{GEN} = 3\Omega$ ,		27.5		ns
Turn-ON Fall Time	t <sub>f</sub>	I <sub>D</sub> =6A		4		ns
Total Gate Charge	Qg	V <sub>DS</sub> = 10V,		6.5		nC
Gate-Source Charge	Qgs	V <sub>GS</sub> = 4.5V,		1.5		nC
Gate-Drain Charge	$Q_{gd}$	I <sub>D</sub> = 6A	-	1.3		nC

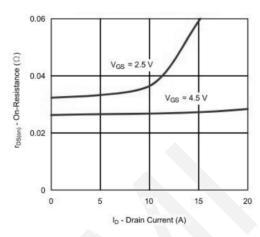
Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



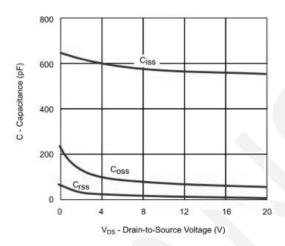
# 7. Typical electrical and thermal characteristics



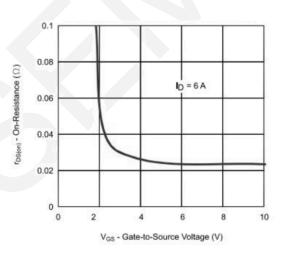
**Transfer Characteristics** 



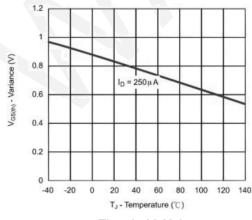
On-Resistance vs. Drain Current



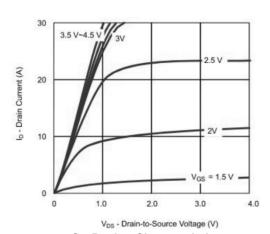
Capacitance



On-Resistance vs. Gate-to-Source Voltage

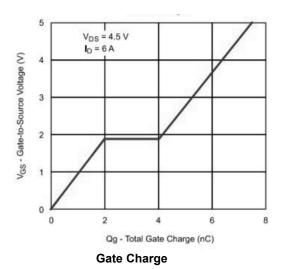


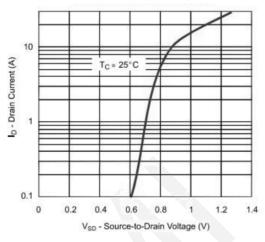




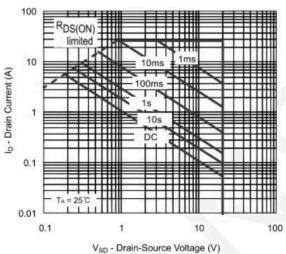
**On-Region Characteristics** 



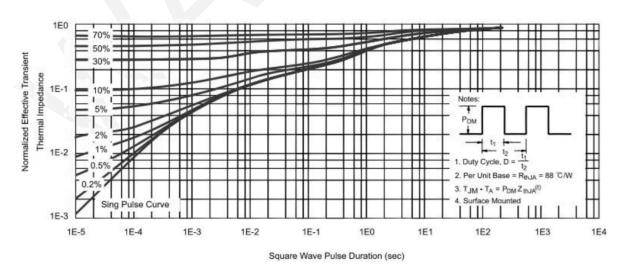




**On-Resistance vs. Drain Current** 



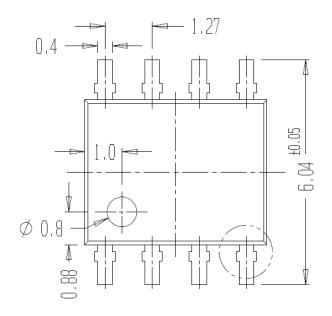
Maximum Forward Biased Safe
Operating Area

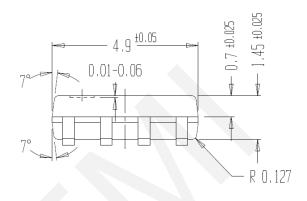


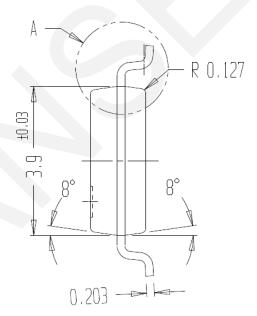
Normalized Thermal Transient Impedance, Junction-to-Ambient



# 8.Package Dimensions









#### 9.Important Notice

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